

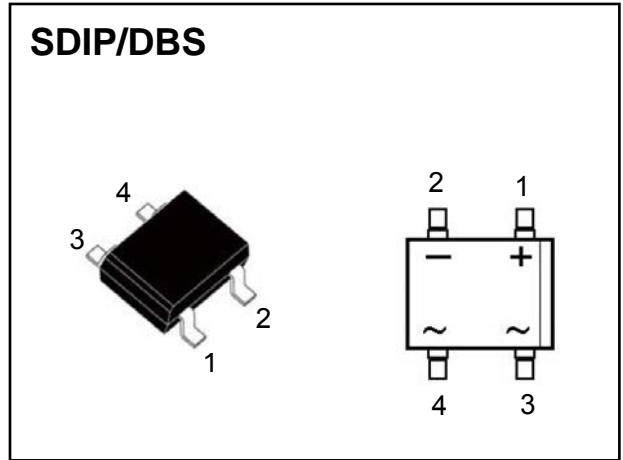


## 1 Amps Surface Mount Bridge

### DB101S-DB107S

#### Features:

- Glass passivated chip junction
- Ideal for surface mounted applications
- High forward surge current capability
- High temperature soldering guaranteed:  
260°C/10 seconds at terminals
- Low leakage



#### Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	DB 101S	DB 102S	DB 103S	DB 104S	DB 105S	DB 106S	DB 107S	Unit
Maximum Reverse Peak Repetitive Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Output Current, 0.06"(1.5mm) lead length at Ta=40°C (Note 1)	$I_{(AV)}$	1							A
Peak Forward Surge Current 8.3ms single half sine wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50							A
Total Device Dissipation Derate above 25°C	$P_D$	5							W
Maximum Reverse Current @ rated $V_R$	$I_R$	5 500							$\mu A$
Maximum Forward Voltage @ 1.0 A	$V_F$	1.1							V
Typical Thermal Resistance (NOTE 1)	$R_{\theta JA}$	40							°C/W
Typical Junction Capacitance @ $V_R = 4.0 V, f = 1.0 MHz$	$C_j$	25							pF
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 to +150							°C

Note :1.Unit mounted on P.C.B. with 0.51"×0.51" ( 13×13mm) copper pads.



### Typical Characteristics

FIG. 1- DERATING CURVE FOR OUTPUT RECTIFIED CURRENT

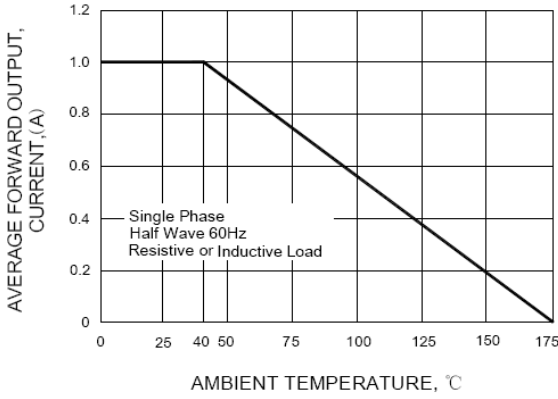


FIG. 2- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER ELEMENT

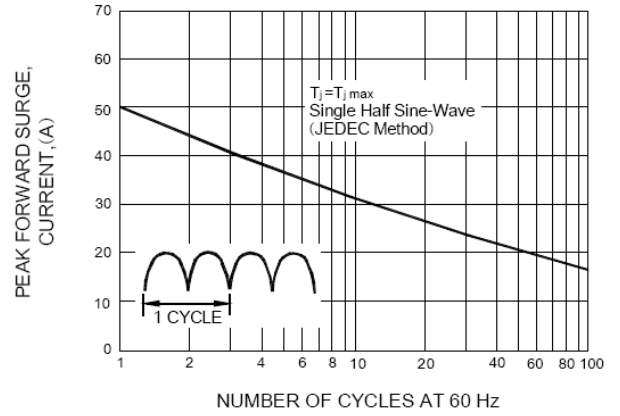


FIG. 3- TYPICAL FORWARD CHARACTERISTICS PER BRIDGE ELEMENT

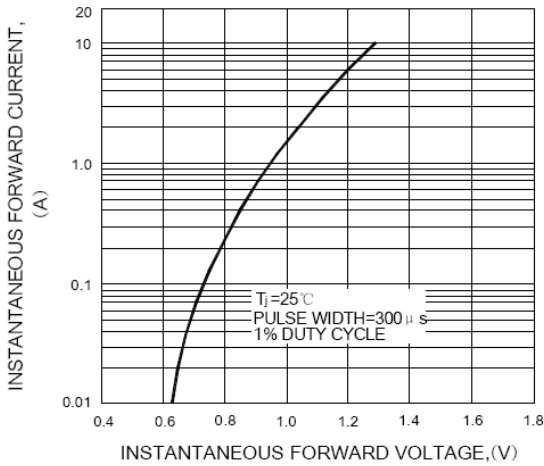


FIG. 4- TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT

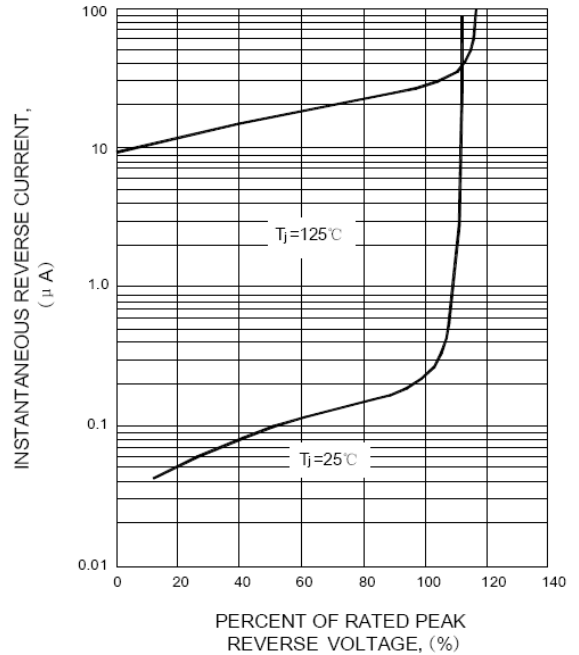
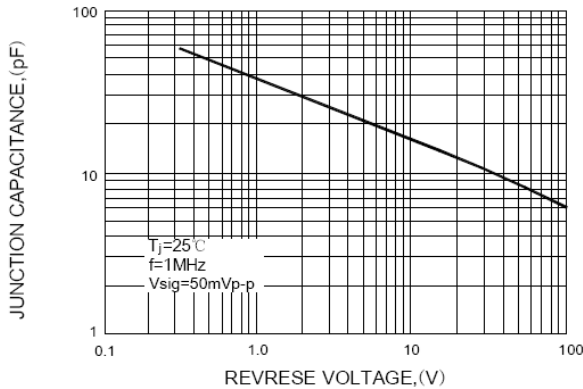


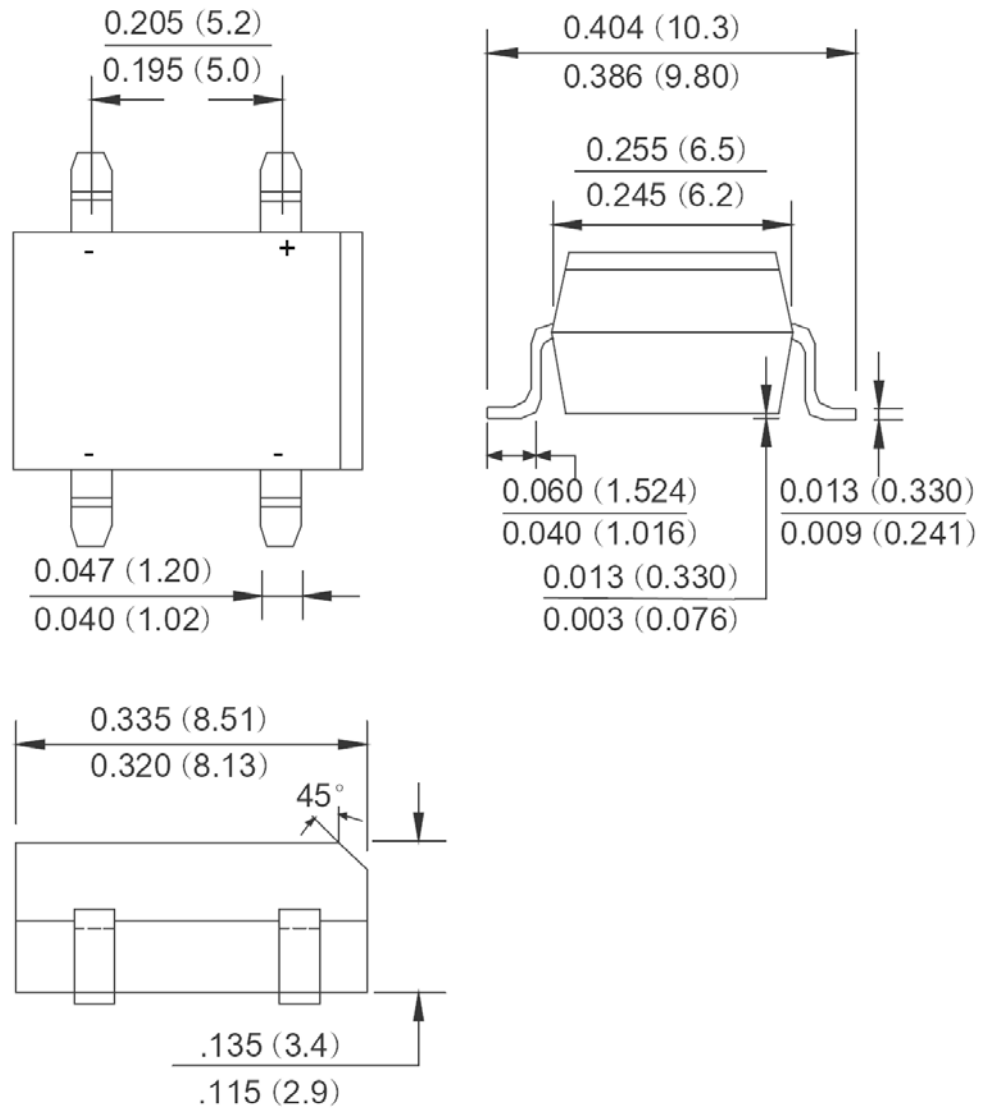
FIG. 5- TYPICAL JUNCTION CAPACITANCE PER BRIDGE ELEMENT





### Package Dimension

#### SDIP/DBS



Dimensions in inches and (millimeters)